

AI Server Chip Substrate Supplier



Overview

Reportedly, the substrate and PCB suppliers focusing on AI servers include Taiwan's three major substrate manufacturers, Japan's leading ABF substrate maker Ibiden, and AT&S. AI Processor Substrates Manufacturer. PCB suppliers include OAM PCB, UBB PCB, and Switch PCB. 3 Dk performance required for high-density AI accelerators. The AI hardware supply chain is critically vulnerable to a single point of failure, with. AI hardware demand has driven PCB raw material prices up 30-40% and lead times from 8 to 20+ weeks. AI server and data. Taiwan's Nan Ya PCB Corporation announces record capital expenditure exceeding NT\$10 billion for 2026, driven by insatiable demand for ABF IC substrates used in AI GPUs, HPC switches, and next-generation server processors. TW), part of Taiwan's Formosa. Application : Primarily applied to core components and peripheral devices within servers, including motherboards, CPU boards, hard disk backplanes, power supply backplanes, memory boards, and network interface cards. AI server PCBs serve as the fundamental electronic platform, connecting and.



Article Content

AI Server Shortage Looms: MSG Maker Ajinomoto Cites ABF

The AI hardware supply chain is critically vulnerable to a single point of failure, with Ajinomoto commanding over 95% market share for the resin material used in CPU and GPU substrates.

Ibiden's \$3.2 Billion Bet on AI: Japan's IC Substrate Giant Plans to ...

Ibiden, the dominant supplier of IC package substrates to NVIDIA and Intel, has announced a massive \$3.2 billion investment plan over three years to boost production capacity

Global Market Intelligence & Consulting | TrendForce

TrendForce offers hi-tech industry research reports, including market bulletins, industry analysis and price trends, helping businesses tackle global challenges

AI Server PCB

AI server PCBs serve as the fundamental electronic platform, connecting and supporting the processors, memory, accelerators, and power management systems required for artificial intelligence

ABF Substrate Market Growth & Forecast [2026-2035]

The ABF (Ajinomoto Build-up Film) Substrate Market serves PCs, servers and data centers, HPC/AI chips, communication equipment like 5G devices, and other sectors including

NVIDIA Corporation

NVIDIA Spectrum-6 Ethernet is the next generation of Ethernet for AI networking, built to scale Rubin-based AI factories with higher efficiency and greater resilience, and enabled by 200G

DIGITIMES: News and Insight of the Global Supply Chain

A platform bridging customers and suppliers Samsung eyes marquee AI win as Anthropic explores custom chip beyond Nvidia Intel deepens ties with Taiwan's

Taiwan AI, kept current: foundry gravity, the Basic | AI in Asia

Taiwan AI, kept current: foundry gravity, the Basic Act and the hardware spine
Taiwan's AI story on one URL: TSMC's foundry dominance and packaging ramp, the AI Basic Act's principles-first

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In fact, we're probably a part of the electronic device you're using right now. Our lithography technology is fundamental to mass producing semiconductor chips. With it, the world's top chipmakers are

2026 Semiconductor Industry Outlook | Deloitte Insights

Deloitte's 2026 global semiconductor industry outlook seeks to identify the strategic issues and opportunities for semiconductor companies and other parts of the semiconductor supply chain to

AI Competition Turns into a Supply Chain Arms Race, Tightening

TrendForce's latest foundry industry findings point out that AI demand has surged rapidly since 2023, leading to capacity bottlenecks in 3 nm–2 nm wafers and 2.5D/3D advanced packaging.

Samsung Electro-Mechanics to expand FC-BGA substrate capacity for AI ...

Competition among FC-BGA suppliers is expected to intensify as AI servers, data center networking equipment and electric vehicle electronics continue to expand. Samsung Electro

Samsung And Sk Hynix Lead Memory Price Hikes As Ai Server

Samsung and SK Hynix are raising DRAM and NAND prices as AI server demand soars. Samsung's HBM4 leadership and AI-driven DRAM growth are expected to reshape the global

Hotter Than a Hot Tub: The 45°C Breakthrough to Cool AI's Biggest ...

NVIDIA's latest AI servers can run on coolant warmer than a hot tub — and that counterintuitive choice is one of the biggest efficiency leaps in data center history.

Samsung & SK Hynix Commit \$518B South Korea Fab Buildout,

The scale of committed CapEx — among the largest coordinated semiconductor investment announcements on record — directly expands future HBM and advanced packaging

Inside the AI Hardware Boom: Servers, Substrates and Advanced

Behind every AI chip and server is a PCB supplier rising to the challenge. Chinese companies like WUS, Gold Circuit (Taiwanese), Shengyi, and Victory Giant saw revenue growth

AI server boom to fuel PCB industry optimism in 2025

Reportedly, the substrate and PCB suppliers focusing on AI servers include Taiwan's three major substrate manufacturers, Japan's leading ABF substrate maker Ibiden, and AT&S. PCB suppliers

Glass Substrates Are Breaking Through the AI Chip Packaging

The AI infrastructure buildout is often discussed in terms of chips and computing power. But beneath the surface, a set of supply chain bottlenecks is quietly shaping the pace and cost of

AI Processor Substrates?

Compact and energy-efficient AI processor substrates support AI inference at the network edge, enabling real-time decision-making and processing in IoT devices, smart cameras, and

Top 10 IC Substrate Manufacturers (2024)

The following is a list of the top 10 IC substrate vendors in 2024 and their manufacturing technologies, R&D focus areas, investments, and developments in the global IC substrate market.

Glass Substrates Are Breaking Through the AI Chip Packaging

This week: glass substrates. Related report: T-Glass Supply Shortages: AI Rack Fiberglass Trends As AI chips grow more complex, package sizes keep expanding, and traditional

Semiconductor Analysis | MicroEval | Artificial Analysis

Put together an estimated supply/demand model for ABF substrates. For supply map out all capacity additions over 2025-2027 and put together a table with each addition, who the supplier is, date of

Glass Substrates vs Organic PCB Packaging: Intel, Samsung Race

Intel and Samsung accelerate glass-core substrate production for AI chip packaging, challenging organic ABF materials with near-silicon CTE matching and sub-2-micron interconnects.

Top 10 Companies in the IC Substrate Packaging Industry (2025):

Here we profile the Top 10 Companies in the IC Substrate Packaging Industry – established leaders and specialized innovators driving the future of microelectronics packaging. 1.

TSMC Accelerates CoPoS Development; Taiwan Panel Makers and

The rapid growth of demand for AI semiconductors is driving the evolution of advanced packaging technologies, with Fan-Out Panel-Level Packaging (FOPLP) emerging as a new

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